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**INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)**



ATTY. DOCKET NO.
005920 USA/
PMG/PCTRL

SERIAL NO.
09/943,383

APPLICANT
SHANMUGASUNDRAM et al.

FILING DATE
August 31, 2001

GROUP
2823

U.S. PATENT DOCUMENTS

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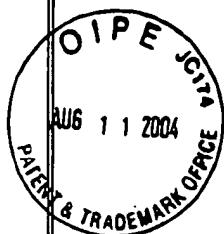
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			APPLICANT SHANMUGASUNDRAM et al.			
			FILING DATE August 31, 2001	GROUP 2823		
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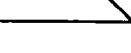
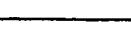
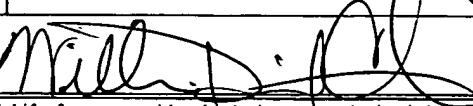
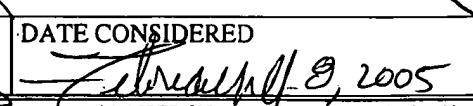
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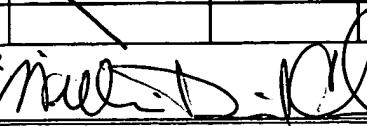
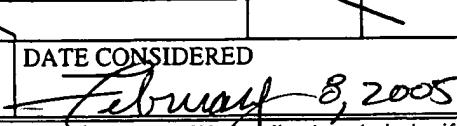
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<p style="text-align: center;">INFORMATION DISCLOSURE CITATION IN AN APPLICATION</p> <p style="text-align: center;">(PTO-1449)</p> <p style="text-align: right; margin-top: -20px;"> </p>		<p>ATTY. DOCKET NO. 005920 USA/ PMG/PCTRL</p> <p>SERIAL NO. 09/943,383</p>
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						Yes	No
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